SHARP	DRAFT	
<u>To;</u>		PEC No. LH22801 SUE: Aug. 01, 2022
SPE	CIFICAT	IONS
Product Name	Laser diode	
Model No.	GH05C01B9G	
Accepted by:	Sharp Corporation	
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Laser diode

Model No. GH05C01B9G

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(5) Please contact and consult with a Sharp sales representative if there are any question regarding interpretation of the above four paragraphs.
3. Disclaimer The warranty period for Sharp product is one (1) year (or six (6) months in case of generalized product) after shipment. During the period, if there are any products problem, Sharp will repair (if applicable), replace or refund. Except the above, both parties will discuss to cope with the problems.
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The warranty described herein is only for Sharp product itself which are purchased by or delivered to customer. Damages arising from Sharp product malfunction or failure shall be excepted.
 Sharp will not be responsible for the Sharp product due to the malfunction or failures thereof which are caused by: (1) storage keep trouble during the inventory in the marketing channel. (2) intentional act, negligence or wrong/poor handling. (3) equipment which Sharp products are connected to or mounted in. (4) disassembling, reforming or changing Sharp products. (5) installation problem. (6) act of God or other disaster (natural disaster, fire, flood, etc.) (7) external factors (abnormal voltage, abnormal electromagnetic wave, fire, etc.) (8) special environment (factory, coastal areas, hotspring area, etc.) (9) phenomenon which cannot be foreseen based on the practical technologies at the time of shipment. (10) the factors not included in the product specification sheet.
4. Please contact and consult with a Sharp sales representative for any questions about Sharp product.



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1. Scope	
This specification covers the appearance and characteris	tics of Green Laser Diode,
Model No. GH05C01B9G	
[Outline of this product]	
This product is equipped with single emitter green laser	diode.
Oscillating transverse mode of this model is TE.	
Oscillating transverse mode of this model is multi-mode.	
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2. Outline Dimensions and Terminal Connections	described in page 2
3. Ratings and Characteristics	described in page 3
4. Reliability	described in page 4
5. Quality level	described in page 5
6. Supplements	
6-1. ODS materials	described in page 5
6-2. RoHS compliant product	described in page 5
6-3. Information relating to China RoHS.	described in page 5
6-4. Packing (Type. 1)	described in page 6
6-5. Packing (Type. 2)	described in page 7
7. Operating and handling precautions	described in page 8



No	Component	Material	Finish	
1	Laser Diode Chip	InAlGaN	_	
2	Stem	Fe, Cu	Gold-plated	
3	Сар	45 alloy	Nickel+Pd plated	
4	Window glass	Borosilicated glass	-	
(5	Lead pins	Kovar	Gold-plated	





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(Tc=25°C)

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3. Ratings and Characteristics

3-1 Absolute Maximum Ratings (Tc=25℃(Note			
Parameter	Symbol	Value	Unit
Operating current (CW)	Iop	1.8	А
Optical power output (CW)	Ро	1.2	W
Reverse voltage	Vr1	2	V
Operating temperature (Case temperature)	Top(c)	$0 \sim +60$	°C
Storage temperature	Tstg	-40 \sim +85	°C
Soldering temperature (Note 2)	Tsld	350	°C

(Note 1) Tc : Case temperature (Tc measurement point is refer to P.2 drowing.)

(Note 2) Soldering temperature means soldering iron tip temperature while soldering.

Soldering position is 1.6mm apart from bottom edge of the case. (Immersion time: \leq 3s)

3-2 Electro-optical Characteristics (Note 1)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Threshold current	Ith	_	-	0.18	0.30	А
Operating current (CW)	Iop		_	1.4	1.79	А
Operating voltage	Vop		_	5.4	6.5	V
Wavelength (Note 4)	λρ		510	520	530	nm
Beam divergence angle(Parallel)(Note 2,3)	θ //	Po=1W	5	9	20	0
Beam divergence angle(Perpendicular)(Note 2,3)	$\theta \perp$	r0-1w	35	44	55	0
Misalignment angle (Parallel) (Note 3)	$\Delta \theta \parallel$		-5	-	5	0
Misalignment angle (Perpendicular) (Note 3)	$\Delta \theta \perp$		-5	-	5	0
Differential efficiency	ηd		0.45	0.8	-	W/A

(Note 1) Initial value, Continuous Wave Operation

(Note 2) Full width angle at $1/e^2$ of peak intensity

(Note 3) Parallel to the junction plane(X-Z plane)

Perpendicular to the junction plane(Y-Z plane)

(Note 4) It is based on method for measurement of light spectrum analyzer Q8344A made by Advantest Corp. of Sharp Corp. property. 3



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4. Reliability

These tests are sampling examples from a specific lot for reference purpose only, and do not constitute any warranty or assurance in connection with the devices.

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4-1 Test items and confidence level

Tested samples should have a laser diode chip with the same structure of this model. These tests are confirmed by performing the operating test under the following conditions in time of development or change process related to the reliability of this product.

		Reference Standards : JIS		Con	nfidence le	vel : 90%
No.	Test	Test Conditions	Samples:n	Defective:C	LTPD (%)	Failure criteria No. [4-2]
1	Solderability	Soldering temperature: 240±5℃(Flux used) Immersion time:5±0.5s	11	0	20	1
2	Resistance to soldering	Soldering iron tip temperature:350+0°C/-5°C Immersion time:3+0s/-1s(Note 1)	11	0	20	3, 4, 5
3	Terminal strength (Tensile test)	Load:5N Duration:5±1s Once for each terminal	11	0	20	2
4	Terminal strength (Bending test)	Load:2.5N $0^{\circ} \sim 90^{\circ} \sim 0^{\circ} \sim -90^{\circ} \sim 0^{\circ}$ Once for each terminal	11	0	20	2
5	Mechanical shock	Acceleration:1,000m/s ² Pulse width:6ms Direction: $\pm X$, $\pm Y$ and $\pm Z$ Three times for each direction	11	0	20	3, 4, 5
6	Variable frequency vibration	Acceleration:100m/s ² or Amplitude:1.5mm Frequency: 10~500~10Hz 15min reciprocation Direction: X,Y and Z 2 h for each direction	11	0	20	3, 4, 5
7	Temperature cycling	Lower temperature:-40°C Higher temperature:+85°C Duration:30min each, 30 times	11	0	20	3, 4, 5
8	High temperature storage	Storage temperature:85°C t=500 h	11	0	20	3, 4, 5
9	Low temperature storage	Storage temperature:-40°C t=500 h	11	0	20	3, 4, 5
10	High temperature Humid atmosphere storage	Storage temperature:60°C (Note 2) humidity:90%RH t=100h	11	0	20	3, 4, 5

(Note 1) Soldering position is 1.6mm apart from bottom edge of the case.

(Note 2) To be measured after 72 hours exposure to the room atmosphere.

4-2 Parameters to be measured and Failure criteria

No.	Parameters	Failure judgment criteria
1	Solderability	95% or more is covered with solder.
2	Terminal strength	It is defective if there are breaking and loosening.
3	Threshold current	Ith $>$ initial value $\times 1.3$, Ith $<$ initial value $\times 0.7$
4	Operating current	Iop $>$ initial value $\times 1.3$, Iop $<$ initial value $\times 0.7$
5	Operating voltage	Vop $>$ initial value $\times 1.2$, Vop $<$ initial value $\times 0.8$

4-3 Lifetime Test

The target mean time to failure (MTTF) of this product is more than 2,000 h. MTTF is confirmed by performing the operating test under the following conditions in time of development or change process related to the reliability of this product.

Samples tested should have a laser diode chip with the same structure of this model.		
Conditions	Failure judgment criteria	
Tc=60℃, CW	Failure is defined as the time under the output power under the conditions	
Iop=1.8A	in the left changes -50% of the initial (12 h) value(Note 1). As for the	
ACC drive(Note 2)	samples which do not fail within 500 hours, their life time is calculated	
500 houres	by extrapolating operating power data of between 400 and 500 hours.	
MTTF is estimated by plotting each life time in Weibull function worksheet. (Note 1		
(Note 1) Defective samples caused by surge current is rejected.		

(Note 2) Automatic current control

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5.Qual	ity level							
5-1 Ins	spection standards	ISO 2	859 single samp	ling plan				
5-2 Ins	spection level	S-2 n	ormal inspectio	n				
5-3 AQL								
5-3-1 D	Definition of the lot	the d	ay shipping the	product				
5-3-2 C	Characteristics (Note	1)			1			
AQL	Parameter				Failure judgment	criteria		
1.0	Ith, Iop, Vop, η d, λ	λр,θ∥,θ.	$\bot, \Delta \theta /\!\!/, \Delta \theta \bot$	-	Not conforming t	o the specific	eations	
5-2-2 1	ppostopao							
<u>5-5-5 A</u> AQL	Failure judgment	criteria						
1.0	Crack is found on		glass.					
v	Bent lead can not		-					
				$50\mu\mathrm{m}$ is found w	vithin 2mmφ to th	ne center of		
	Impurity or dust its size is over $50 \mu\text{m} \times 50 \mu\text{m}$ is found within $2\text{mm}\phi$ to the center of the surface of the window glass. (Note.2)							
2.5	Diameter of stem			cification				
6. Supp	lements							
6-1 ODS	6 materials							
m1 •	product shall not co	ntain the f	ollowing materi	als. Also, the f	ollowing material	s shall not b	e	
This		acces for t						
	in the production pr	ocess for t	his product.					
used	in the production pr rials for ODS : CFCs,		•	de, 1.1.1-Trichl	oroethane (Methy)	chloroform)		
used Mater			•	de, 1.1.1-Trichl	oroethane (Methy]	chloroform)		
used Mater 6-2 RoH	rials for ODS : CFCs,	Halon, Car	bon tetrachlori		oroethane (Methy]	chloroform)		
used Mater 6-2 RoH This	ials for ODS : CFCs, IS compliant product product complies wit	Halon, Car h EU RoHS D	bon tetrachlori irective (2011/		oroethane (Methy]	chloroform)		
used Mater 6-2 RoH This	rials for ODS : CFCs, IS compliant product	Halon, Car h EU RoHS D	bon tetrachlori irective (2011/		oroethane (Methy]	chloroform)		
used Mater 6-2 RoH This Commi	ials for ODS : CFCs, IS compliant product product complies wit	Halon, Car h EU RoHS D ctive (EU)2	bon tetrachlori irective (2011/ 015/863.		oroethane (Methy]	chloroform)		
used Mater 6-2 RoH This Commi 6-3 Inf	rials for ODS : CFCs, IS compliant product product complies wit assion Delegated Dire	Halon, Car h EU RoHS D ctive (EU)2 China RoHS	bon tetrachlori irective (2011/ 015/863.	'65/EU) and			on	
used Mater 6-2 RoH This Commi 6-3 Inf Produ	Fials for ODS : CFCs, IS compliant product product complies wit Ession Delegated Dire Cormation relating to	Halon, Car h EU RoHS D ctive (EU)2 China RoHS ication bas	bon tetrachlori irective (2011/ 015/863.	'65/EU) and			on	
used Mater 6-2 RoH This Commi 6-3 Inf Produ	rials for ODS : CFCs, IS compliant product product complies wit ssion Delegated Dire formation relating to act Information Notif	Halon, Car h EU RoHS D ctive (EU)2 China RoHS ication bas	bon tetrachlori irective (2011/ 015/863.	'65/EU) and			on	
used Mater 6-2 RoH This Commi 6-3 Inf Produ by El	rials for ODS : CFCs, IS compliant product product complies wit ssion Delegated Dire formation relating to act Information Notif	Halon, Car h EU RoHS D ctive (EU)2 China RoHS ication bas Products.	bon tetrachlori irective (2011/ 015/863. ed on Chinese 1	'65/EU) and aw, Management M	ethods for Contro		on	
used Mater 6-2 RoH This Commi 6-3 Inf Produ by El	Tials for ODS : CFCs, IS compliant product product complies wit assion Delegated Dire formation relating to act Information Notif ectronic Information s and Contents of the	Halon, Car h EU RoHS D ctive (EU)2 China RoHS ication bas Products. <u>Toxic and</u>	bon tetrachlori irective (2011/ 015/863. ed on Chinese 1 Hazardous Subst	'65/EU) and aw, Management M	ethods for Contro	Polybrominat	_	
used Mater 6-2 RoH This Commi 6-3 Inf Produ by El	Tials for ODS : CFCs, IS compliant product product complies wit assion Delegated Dire Cormation relating to act Information Notif ectronic Information s and Contents of the Lead Me	Halon, Car h EU RoHS D ctive (EU)2 China RoHS ication bas Products.	bon tetrachlori irective (2011/ 015/863. ed on Chinese 1	'65/EU) and aw, Management M cances or Element Hexavalent Chromium	ethods for Contro s in the Product Polybrominated Biphenyls	Polybrominat Diphenyl Ethers	_	
used Mater 6-2 RoH This Commi 6-3 Inf Produ by El	Tials for ODS : CFCs, IS compliant product product complies wit assion Delegated Dire Cormation relating to act Information Notif ectronic Information s and Contents of the Lead Me	Halon, Car h EU RoHS D ctive (EU)2 China RoHS ication bas Products. <u>Toxic and</u> rcury	bon tetrachlori irective (2011/ 015/863. ed on Chinese 1 <u>Hazardous Subst</u> Cadmium	'65/EU) and aw, Management M ances or Element Hexavalent	ethods for Contro s in the Product Polybrominated	Polybrominat Diphenyl	_	

This table was created pursuant to the provisions of SJ / T 11364.

 \bigcirc : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in GB/T26572.

 \times : indicates that the content of the toxic and hazardous substance in at least one homogeneous material of the part exceeds the concentration limit requirement as described in GB/T26572 standard.





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6-4. Packing (Type. 1)

Note) This model has 2 way packing type. This packing method is applied to GH05C01B9G made in Indonesia. 6-4-1. Packing method

- $\left(1\right)$ Laser diodes are arranged in a laser tray.
- (2) One tray can accommodate 200 lasers. 5 trays wherein the laser diodes are arranged are stacked up.
- (3) The empty tray and the tray cover is stacked as a cover on the tray wherein the laser diodes are arranged. Stacked trays including a cover are bound with adhesive tape.
- (4) The above bound trays are stuffed into a clean-bag. The bag is sealed by dissolving thermally.
- (5) The trays in the bag are put into a packing case. One packing case can accommodate 1,000 lasers maximum. A Label where in the model number, quantity and lot number are printed is stuck on both of the bag and the case(Refer to 6-4-4).

6-4-2. Materials for packing

Component parts	Material
Laser tray	conductive polystyrene resin
Cover tray	conductive polystyrene resin
Clean-bag	anti–static plastic
Packing case	cardboard
shock absorber	anti – static polyetyrene
	Laser tray Cover tray Clean-bag Packing case







6-4-4. Label









(Note 1) ****:Production country

- (Note 2) A management number in the factory is written in (), if the product produced in a factory except Japan.
- (Note 3) This identification mark shows the settlement product for RoHS designed by using a green material based on our green device guideline.





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6-5. Packing (Type. 2)

Note) This model has 2 way packing type. This packing method is applied to GH05C01B9G made in Taiwan. 6-5-1. Packing method

- (1) Laser diodes are arranged in a laser tray.
- (2) One tray can accommodate 50 lasers.
- (3) A cover is stacked on the tray wherein the laser diodes are arranged. Tray including a cover are bound with adhesive tape.
- (4) The above bound trays are stuffed into a clean-bag. The bag is sealed by dissolving thermally.
- (5) The trays in the bag are put into a packing case (Max 30 trays). One packing case can accommodate 1,500 lasers maximum. A Label where in the model number ,quantity and lot number are printed is stuck on both of the bag and the case(Refer to 6-5-4).

6-5-2. Materials for packing

No.	Component parts	Material
1	Laser tray	conductive polystyrene resin
2	Cover tray	conductive polystyrene resin
3	Clean-bag	anti–static plastic
4	Packing case	cardboard
5	shock absorber	anti – static polyetyrene









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- 7. Operating and handling precautions
- This product has its life. The product life which is described in "Reliability" should be taken into account when using it.
- (2) This product will be damaged by electrostatic discharge(ESD). Following precautions should be taken to avoid ESD damage.

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- \Rightarrow Workers, workbenches and other equipment should always be grounded. Workers should always wear an antistatic wrist strap and an antistatic smock on them.
- \Rightarrow When handling this product, workers should always wear antistatic gloves or finger covers.
- \Rightarrow A stable DC power supply which is free from electrical transients should always be used when operating this product. A slow starter circuit should always be inserted between the power supply and this product in order to protect it from DC power surges.
- \Rightarrow Optical power output of this product should be set with a highly reliable and high quality variable resistance.
- \Rightarrow This product should always be connected to the driving circuit by soldering directly or through highly reliable connectors.
- \Rightarrow While this product is being operated, be sure to avoid touching the driving circuit or the terminals of this product with electrical probes from a synchroscope or a voltmeter.
- ⇒ An antistatic package should be used when storing this product. The recommended preservation is stored in the tray and the clean-bag in an environmental condition dry at normal temperature $(0 \sim 40^{\circ} \text{C})$
- \Rightarrow This product should be processed in the rooms where relative humidity is kept at 50-70%RH.

(3) This product doesn't do the design that intends use in the following, special environment. Please use it after confirming the performance and reliability, etc. enough in your company before use in the following special environment.

 $\Rightarrow Use$ in place where a lot of moisture, be dewys, sea breezes, or causticity gases (Cl, H2S, NH3, S02, and N0X, etc.) exist.

- \Rightarrow Use under direct sunshine, in out-of-door exposure, or in dust.
- \Rightarrow Use in atmosphere such as water, oil, drug solutions, or organic solvents.
- $\Rightarrow \! \textsc{Use}$ in environment with strong static electricity or electromagnetic radiation.
- \Rightarrow Use in state installed near generation of heat parts or in state to arrange combustible near this product.
- (4)Because the adhesion of garbage and dust to the window glass might disarrange an optical characteristic of this product, maintain the work room to cleanness so as not generate dust, please.
- (5) In this product, generation of heat happens in the laser chip because of operating. The case temperature rises by this generation of heat. Because the rise of the case temperature becomes a factor to shorten the lifetime of this product, a sufficient heat sink should be attached to this product when operating so that its case temperature is to be maintained at the same level as that of the surrounding.
- (6) Even if the drive current supply has an automatic power control (APC), automatic current control (ACC), or both, be sure to monitor the optical power output with an optical power meter while setting it. Never estimate the optical power output only from the drive current because it is likely to be decreased by temperature rise of the surrounding.
- (7)When dirt adheres to the window glass of this product, please wipe lightly with the cotton bud that adheres the ethanol.
- (8) This product consists of a hermetic package, in which the green laser diode chip is mounted. The green laser diode chip will be easily damaged by air, moisture or etc. So when the package does not keep hermetically, the lifetime of this product will be remarkably shorten.

Following precautions should be taken to avoid destroying the hermetic package. \Rightarrow The window glass cracks easily because it is thin.

Please do not give an impact to the window glass by dropping this product.

Please avoid applying the stress to the cap, for example clumping, tightening hard, or fixing to the treatment device.

⇒Because applying the overstress to the lead pin or repeating to bend the lead pin at its bottom, will destroy the hermetic seal. Please do not apply the overstress to the base part of lead pin.

- ⇒When a large stress is applied to the package, please confirm whether the package is kept hermetically before using this product.
- (9) Since laser beam from this product will be harmful to the human eyes, the following precautions should be taken.
 - \Rightarrow When this product is being operated, the emitting surface of a chip should not be viewed either directly or through a lens, microscope or optical fibers.
 - \Rightarrow When operating this product, wear safety glasses.
- (10) When soldering this product, heat lead pins only using a soldering iron in short time. Avoid heat the whole package using pre-heat or reflow soldering.